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Dated: May 2, 2006

Signature: 
(Richard H. Anderson)

Docket No.: 27702/10065
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

By Patent Application of:
Gary Wentworth et al.

Application No.: 10/706,196

Confirmation No.: 5990

Filed: November 12, 2003

Art Unit: 1614

For: ADHESION PROMOTERS FOR CORD-
REINFORCED THERMOPLASTIC
POLYMERIC MATERIALS AND
SUBSTRATE/THERMOPLASTIC
POLYMERIC MATERIAL COMPOSITES

Examiner: S. K. Poulos

AMENDMENT IN RESPONSE TO NON-FINAL OFFICE ACTION

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

INTRODUCTORY COMMENTS

In response to the Office Action dated February 17, 2006, please amend the above-identified U.S. patent application as follows:

Amendments to the Abstract begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

Remarks/Arguments begin on page 24 of this paper.